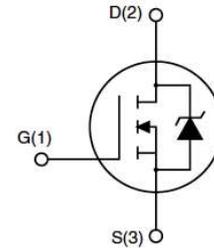


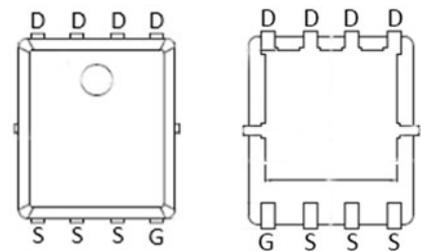
## Feature

- 120V,106A  
 $R_{DS(ON)} < 8.0m\Omega @ V_{GS}=10V$  (TYP:6.5m $\Omega$ )
- Split Gate Trench Technology
- Lead free product is acquired
- Excellent  $R_{DS(ON)}$  and Low Gate Charge



## Application

- PWM applications
- Load Switch
- Power management



PDFN5X6

## Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)
G080N12G	APG080N12G	PDFN5X6	-	-	5000

## ABSOLUTE MAXIMUM RATINGS ( $T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	120	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current ( $T_a=25^\circ\text{C}$ )	$I_D$	106	A
Continuous Drain Current ( $T_a=100^\circ\text{C}$ )	$I_D$	67	A
Pulsed Drain Current <sup>(1)</sup>	$I_{DM}$	424	A
Single Pulsed Avalanche Energy <sup>(2)</sup>	$E_{AS}$	480	mJ
Power Dissipation	$P_D$	147	W
Thermal Resistance from Junction to Case	$R_{\theta JC}$	0.85	$^\circ\text{C}/\text{W}$
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55~ +150	$^\circ\text{C}$

**MOSFET ELECTRICAL CHARACTERISTICS(T<sub>a</sub>=25°C unless otherwise noted)**

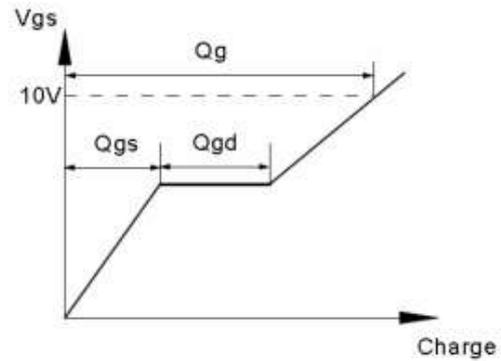
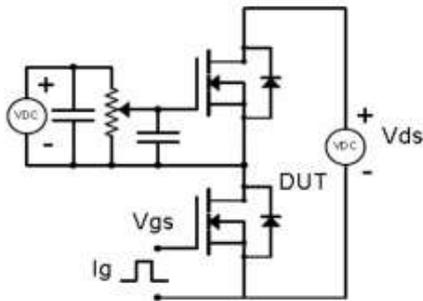
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =250μA	120	-	-	V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =120V, V <sub>GS</sub> = 0V	-	-	1	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> =± 20V, V <sub>DS</sub> = 0V	-	-	±100	nA
Gate threshold voltage <sup>(3)</sup>	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.0	3.0	4.0	V
Drain-source on-resistance <sup>(3)</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =40A	-	6.5	8.0	mΩ
<b>Dynamic characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V, f =1MHz	-	3770	-	pF
Output Capacitance	C <sub>oss</sub>		-	352	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	17	-	
<b>Switching characteristics</b>						
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> =50V, I <sub>D</sub> =50A, V <sub>GS</sub> =10V, R <sub>G</sub> =3Ω	-	22	-	ns
Turn-on rise time	t <sub>r</sub>		-	18	-	
Turn-off delay time	t <sub>d(off)</sub>		-	49	-	
Turn-off fall time	t <sub>f</sub>		-	19	-	
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =50V, I <sub>D</sub> =50A, V <sub>GS</sub> =10V	-	56	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	12	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	14	-	
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> =30A, di/dt=100A/us		102		nC
Reverse Recovery Time	T <sub>rr</sub>	I <sub>F</sub> =30A, di/dt=100A/us		66		ns
<b>Source-Drain Diode characteristics</b>						
Diode Forward voltage <sup>(3)</sup>	V <sub>DS</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =50A	-	-	1.3	V
Diode Forward current <sup>(4)</sup>	I <sub>S</sub>		-	-	106	A

**Notes:**

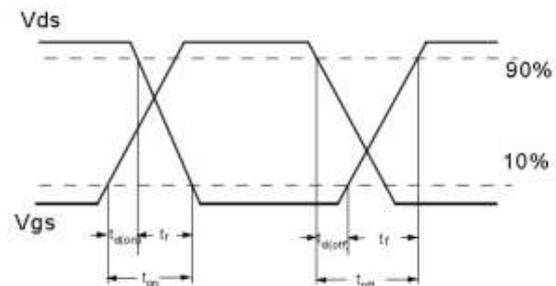
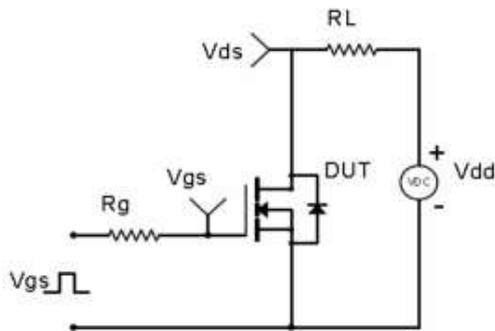
1. Repetitive Rating: pulse width limited by maximum junction temperature
2. EAS Condition: T<sub>J</sub>=25°C, V<sub>DD</sub>=50V, R<sub>G</sub>=25 Ω, L=0.5Mh
3. Pulse Test: pulse width≤300μs, duty cycle≤2%
4. Surface Mounted on FR4 Board, t≤10 sec

**Test Circuit & Waveform**

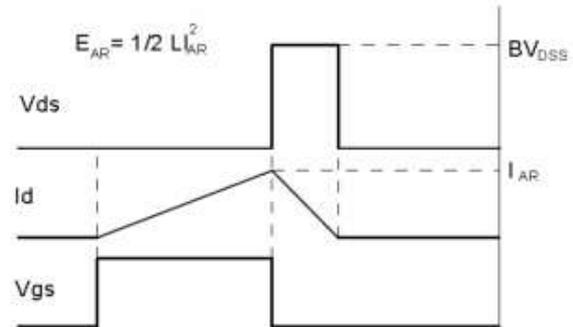
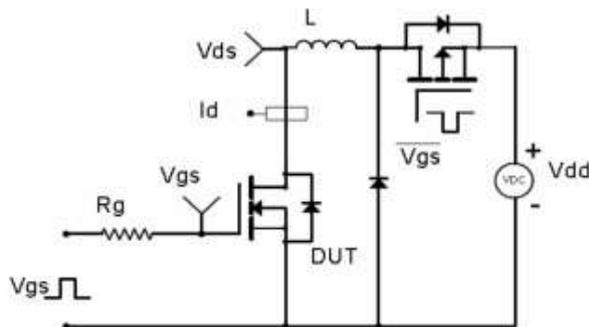
Gate Charge Test Circuit & Waveform



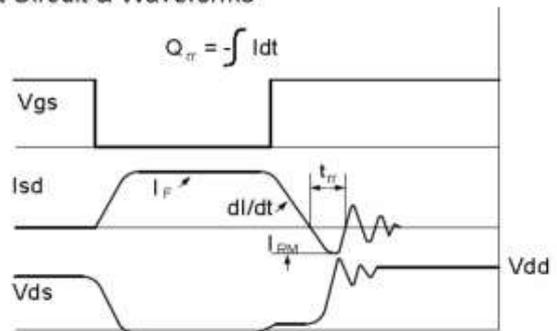
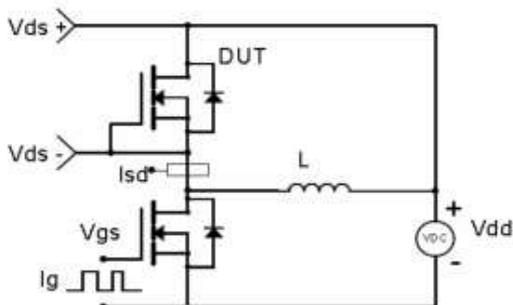
Resistive Switching Test Circuit & Waveforms



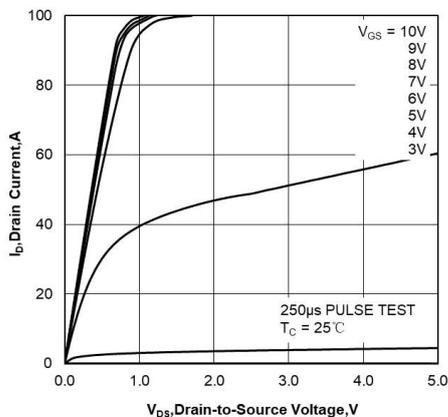
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



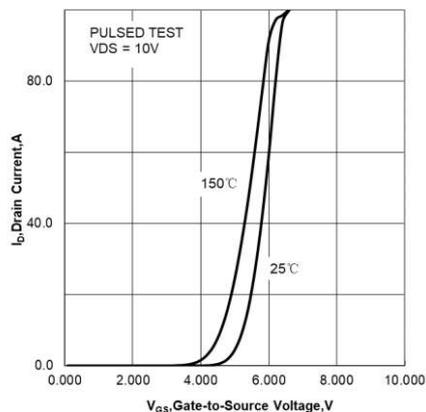
Diode Recovery Test Circuit & Waveforms



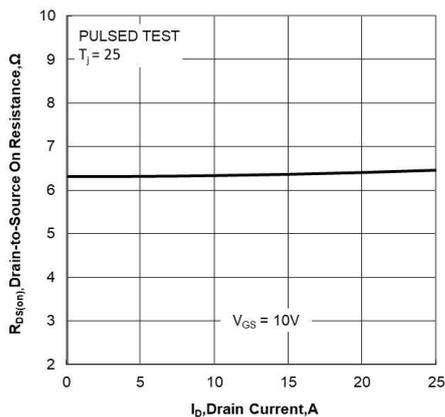
**Typical Performance Characteristics**



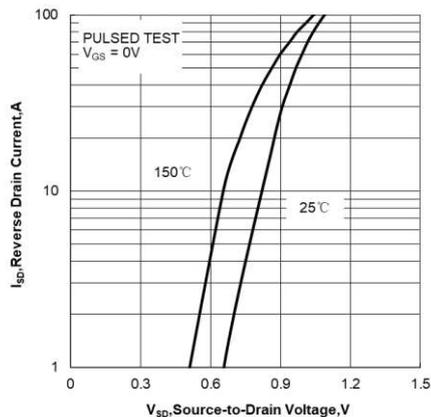
**Figure 1. Output Characteristics**



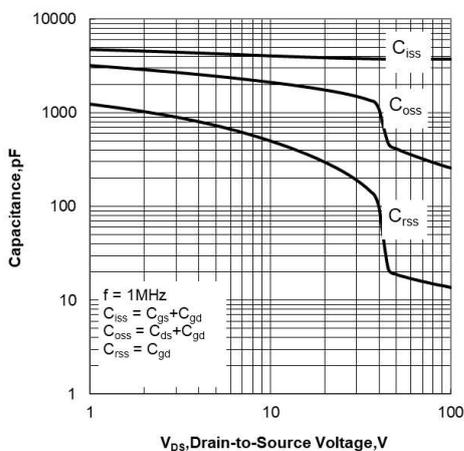
**Figure 2. Transfer Characteristics**



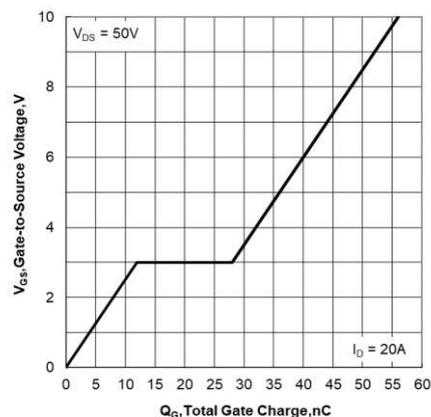
**Figure 3. Drain-to-Source On Resistance vs Drain Current**



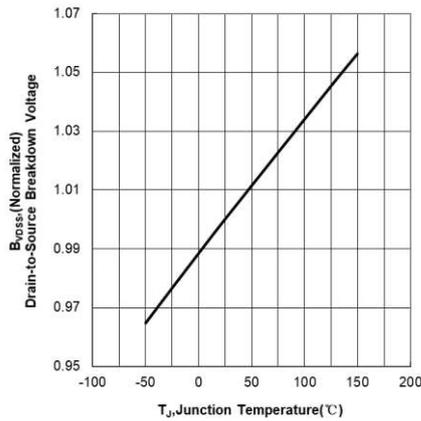
**Figure 4. Body Diode Forward Voltage vs Source Current and Temperature**



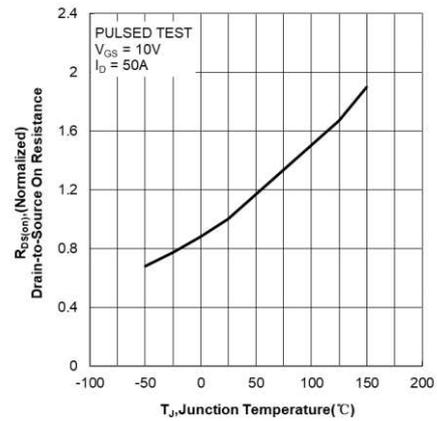
**Figure 5. Capacitance Characteristics**



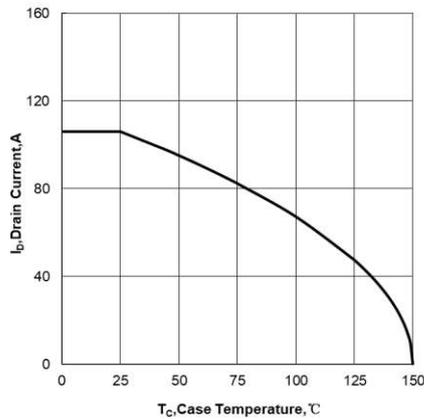
**Figure 6. Gate Charge Characteristics**



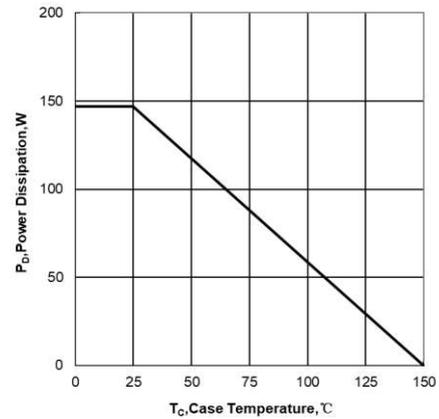
**Figure 7. Normalized Breakdown Voltage vs Junction Temperature**



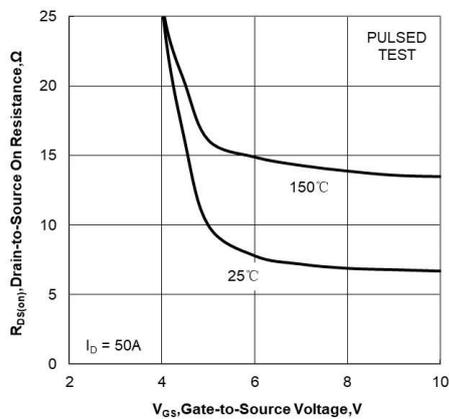
**Figure 8. Normalized On Resistance vs Junction Temperature**



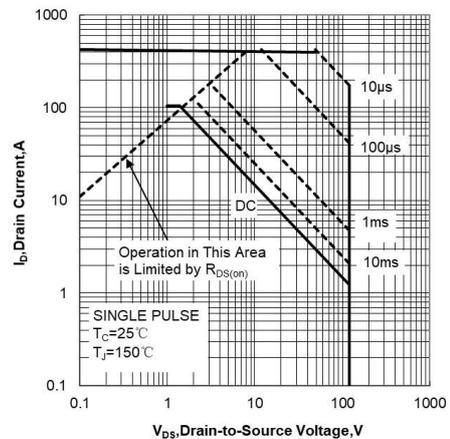
**Figure 9. Maximum Continuous Drain Current vs Case Temperature**



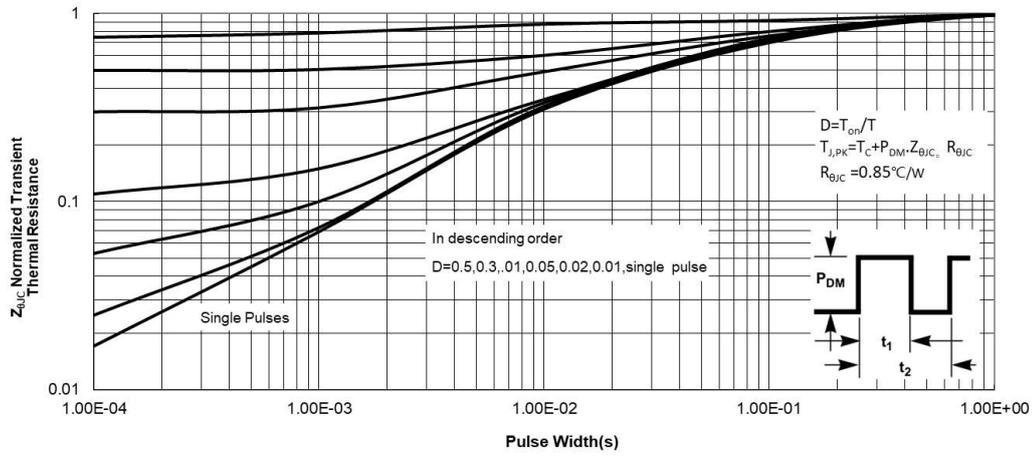
**Figure 10. Maximum Power Dissipation vs Case Temperature**



**Figure 11. Drain-to-Source On Resistance vs Gate Voltage and Drain Current**

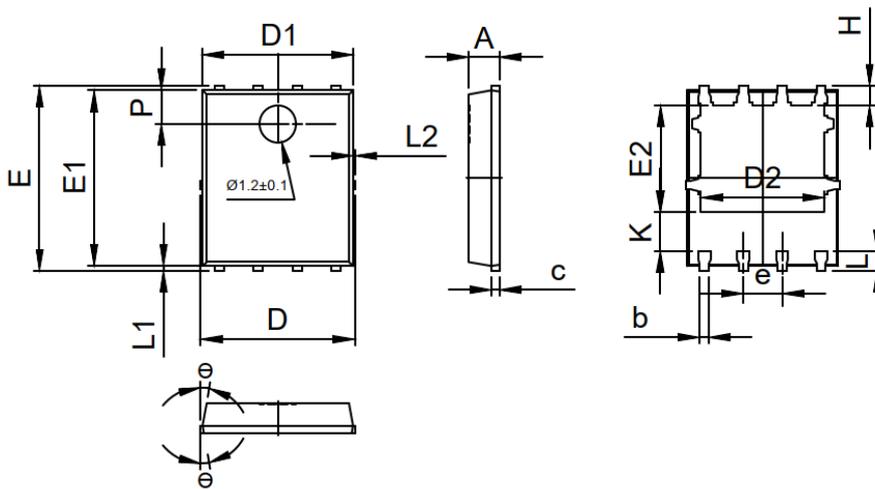


**Figure 12. Maximum Safe Operating Area**



**Figure 13. Maximum Effective Transient Thermal Impedance, Junction-to-Case**

**PDFN5X6 Package Information**



SYMBOL	MIN	NOM	MAX
A	0.90	1.00	1.10
b	0.25	0.30	0.35
c	0.21	0.25	0.34
D	-	-	5.10
D1	4.80	4.90	5.00
D2	3.91	4.01	4.11
e	1.27 BSC		
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.375	3.475	3.575
H	0.55	0.65	0.75
K	1.20	-	-
L	0.55	0.65	0.75
L1	0.05	0.15	0.25
L2	-	-	0.12
$\theta$	8°	10°	12°
P	1.00	1.10	1.20